



PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

282,78  
#9/B  
5/15/02

In re application of

Shanabu MIZUSAKI

Serial No. 09/847,370

GROUP 2827

Filed May 3, 2001

Examiner James M. Mitchell

ELECTRODE STRUCTURE OF A  
CARRIER SUBSTRATE OF A SEMI-  
CONDUCTOR DEVICE

SUPPLEMENTAL AMENDMENT

RECEIVED  
APR 23 2002  
2800 MAIL ROOM

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of January 16, 2002  
and supplemental to the amendment of April 16, 2002, please amend  
the above-identified application as follows:

IN THE CLAIMS:

Add the following new claims:

--16. (new) An electrode structure of a carrier  
substrate of a semiconductor device for solder-bonding the  
semiconductor device to a main substrate, comprising:

a recess formed in a central area of the electrode  
structure;

a circumferential wall surface surrounding said recess  
of said central area; and

a through portion passing through said circumferential  
wall surface and connecting between an inside portion of said  
recess and an outer portion of said circumferential wall surface.

Sub  
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